

MPC5554 Microcontroller Product Brief

The MPC5554 is the first member of a family of next generation microcontrollers based on the PowerPC™ Book E architecture that enhances the PowerPC architecture's fit in embedded applications. It is 100% user mode compatible (with floating point library) with the classic PowerPC instruction set. This document provides an overview of the MPC5554 microcontroller features, including the major functional components.

The MPC5554 device's on-chip modules include the following:

- Single issue, 32-bit PowerPC Book E-compliant e200z6 CPU core complex
- 64-channel enhanced direct memory access controller (eDMA)
- Interrupt controller (INTC) capable of handling 286 selectable-priority interrupt sources
- Frequency modulated phase-locked loop (FMPLL)
- External bus interface (EBI) with error correction status module (ECSM)
- System integration unit (SIU)

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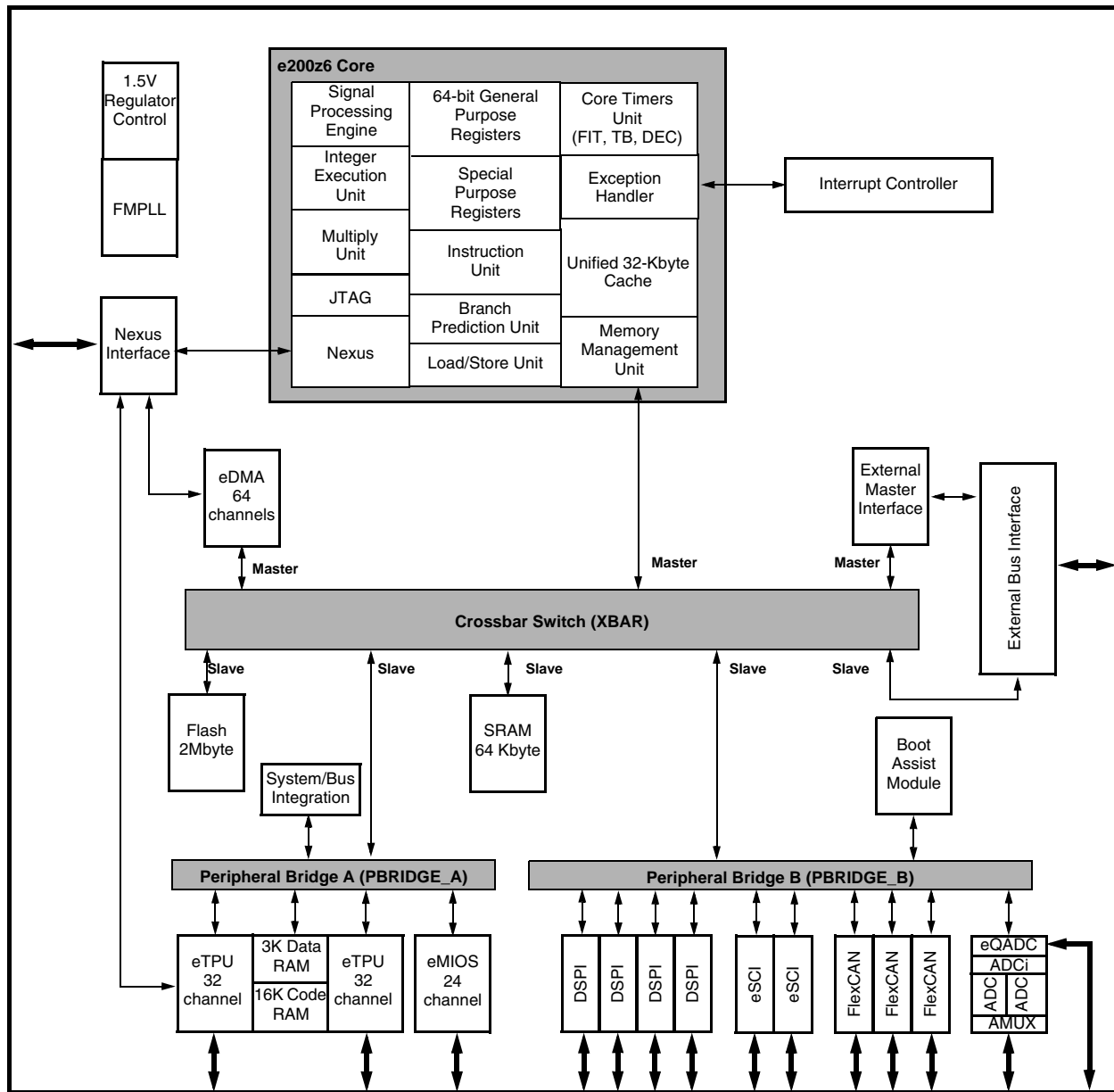
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- 2 Mbytes on-chip Flash with Flash bus interface unit (FBIU)
- 64 Kbytes on-chip static RAM
- Boot assist module (BAM)
- 24-channel enhanced modular I/O system (eMIOS)
- 2 enhanced time processor unit (eTPU) engines. Each eTPU engine controls 32 hardware channels.
- Enhanced queued analog-to-digital converter (eQADC)
- 4 deserial serial peripheral interface (DSPI) modules
- 2 enhanced serial communication interface (eSCI) modules
- 3 controller area network (FlexCAN) modules
- Nexus development interface (NDI) per IEEE-ISTO 5001-2003 standard
- Device/board test support per Joint Test Action Group (JTAG) of IEEE (IEEE 1149.1)

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1 Block Diagram

Figure 1 shows a top-level block diagram of the MPC5554.



LEGEND

MPC5500 Device Module Acronyms

- CAN – Controller area network (FlexCAN)
- DSPI – Deserial/serial peripheral interface
- DMA – Enhanced direct memory access
- eMIOS – Enhanced modular I/O system
- eQADC – Enhanced queued analog/digital converter
- eSCI – Enhanced serial communications interface
- eTPU – Enhanced time processing units
- FMPLL – Frequency modulated phase-locked loop
- SRAM – Static RAM

e200z6 Core Component Acronyms

- DEC – Decrementer
- FIT – Fixed interval timer
- TB – Time base
- WDT – Watchdog timer

Figure 1. MPC5554 Block Diagram

2 Features

This section provides a high-level description of the major features of the MPC5554.

- High performance e200z6 core processor
 - 32-bit PowerPC Book E compliant CPU
 - 32 64-bit general-purpose registers (GPRs)
 - Memory management unit (MMU) with 32-entry, fully-associative translation look-aside buffer (TLB)
 - Branch processing unit
 - Fully pipelined load/store unit
 - 32-Kbyte unified cache with line locking
 - 8-way set associative
 - 2 32-bit fetches per clock
 - 8-entry store buffer
 - Way locking
 - Supports assigning cache as instruction or data only on a per way basis
 - Supports tag and data parity
 - Vectored interrupt support
 - Interrupt latency < 70 ns @132MHz (measured from interrupt request to execution of first instruction of interrupt exception handler)
 - Reservation instructions for implementing read-modify-write constructs (internal SRAM and Flash)
 - Signal processing engine (SPE) auxiliary processing unit (APU) operating on 64-bit GPRs
 - Floating point
 - IEEE® 754 compatible with software wrapper
 - Single precision in hardware and double precision with software library
 - Conversion instructions between single precision floating point and fixed point
 - Long cycle time instructions, except for guarded loads, do not increase interrupt latency in the MPC5554. To reduce latency, long cycle time instructions are aborted upon interrupt requests.
 - Extensive system development support through Nexus debug module
- Crossbar switch (XBAR)
 - 3 master ports; 5 slave ports
 - 32-bit address bus; 64-bit data bus
 - Simultaneous accesses from different masters to different slaves (there is no clock penalty when a parked master accesses a slave)

- Enhanced direct memory access (eDMA) controller
 - 64 channels support independent 8-, 16-, 32-, or 64-bit single value or block transfers
 - Supports variable sized queues and circular queues
 - Source and destination address registers are independently configured to post-increment or remain constant
 - Each transfer is initiated by a peripheral, CPU, or eDMA channel request
 - Each eDMA channel can optionally send an interrupt request to the CPU on completion of a single value or block transfer
- Interrupt controller (INTC)
 - 308 total interrupt vectors
 - 278 peripheral interrupt requests
 - plus 8 software settable sources
 - plus 22 reserved interrupts
 - Unique 9-bit vector per interrupt source
 - 16 priority levels with fixed hardware arbitration within priority levels for each interrupt source
 - Priority elevation for shared resources
- Frequency modulated phase-locked loop (FMPLL)
 - Input clock frequency from 8 MHz to 20 MHz
 - Current controlled oscillator (ICO) range from 50 MHz to maximum device frequency
 - Reduced frequency divider (RFD) for reduced frequency operation without re-lock
 - 4 selectable modes of operation
 - Programmable frequency modulation
 - Lock detect circuitry continuously monitors lock status
 - Loss of clock (LOC) detection for reference and feedback clocks
 - Self-clocked mode (SCM) operation
 - On-chip loop filter (reduces number of external components required)
 - Engineering clock output
- External bus interface (EBI)
 - 1.8V–3.3V I/O nominal I/O voltage
 - Memory controller with support for various memory types
 - 32-bit data bus and 24-bit address bus with transfer size indication
 - Selectable drive strength
 - Configurable bus speed modes
 - Support for external master accesses to internal addresses
 - Burst support

Features

- Bus monitor
- Chip selects: 4 chip select ($\overline{\text{CS}}[0:3]$) signals
- Configurable wait states
- System integration unit (SIU)
 - Centralized GPIO control of 214 I/O and bus pins
 - Centralized pad control on a per-pin basis
 - System reset monitoring and generation
 - External interrupt inputs, filtering, and control
- Error correction status module (ECSM)
 - Configurable error-correcting codes (ECC) reporting for internal SRAM and Flash memories
- On-chip Flash
 - 2 Mbytes burst Flash memory
 - 256K × 64 bit configuration
 - Censorship protection scheme to prevent Flash content visibility
 - Hardware read-while-write feature that allows blocks to be erased/programmed while other blocks are being read (used for EEPROM emulation and data calibration)
 - 20 blocks, ranging from 16 Kbytes to 128 Kbytes, to support features such as boot block, operating system block, and EEPROM emulation
 - Read while write with multiple partitions
 - Parallel programming mode to support rapid end of line programming
 - Hardware programming state machine
- Configurable cache memory, 32-Kbyte
 - 8-way set-associative, unified (instruction and data) cache
- On-chip, internal static RAM (SRAM)
 - 64-Kbyte general-purpose RAM; 32 Kbytes on standby power
 - ECC performs single bit correction, double bit error detection
- Boot assist module (BAM)
 - Enables and manages the transition of MCU from reset to user code execution in the following configurations:
 - User application can boot from internal or external Flash memory
 - Download and execution of code via FlexCAN or eSCI
- Enhanced modular I/O system (eMIOS)
 - 24 orthogonal channels with double action, PWM, and modulus counter functionality
 - Supports all DASM and PWM modes of MIOS14 (MPC5xx)
 - 4 selectable time bases plus shared time or angle counter bus
 - DMA and interrupt request support

- Motor control capability
- Enhanced time processor unit (eTPU)
 - MPC5554 has 2 eTPU engines
 - Each eTPU engine is an event-triggered timer subsystem
 - High level assembler/compiler
 - 32 channels per engine
 - 24-bit timer resolution
 - 16-Kbyte shared code memory
 - 3-Kbyte shared data memory
 - Variable number of parameters allocatable per channel
 - Double match/capture channels
 - Angle clock hardware support
 - Shared time or angle counter bus for all eTPU and eMIOS modules
 - DMA and interrupt request support
 - Nexus Class 3 Debug support (with some Class 4 support)
- Enhanced queued analog/digital converter (eQADC)
 - 2 independent ADCs with 12-bit A/D resolution
 - Common mode conversion range of 0–5V
 - 40 single-ended inputs channels, expandable to 65 channels with external multiplexers
 - 4 pairs of differential analog input channels.
 - 10-bit accuracy at 400 ksamples/s, 8-bit accuracy at 800 ksamples/s
 - Supports 6 FIFO queues with fixed priority.
 - Queue modes with priority-based preemption; initiated by software command, internal (eTPU and eMIOS), or external triggers
 - DMA and interrupt request support
 - Supports all functional modes from QADC (MPC5xx family)
- 4 Deserial serial peripheral interface modules (DSPI)
 - Serial peripheral interface (SPI)
 - Full duplex communication ports with interrupt and eDMA request support
 - Supports all functional modes from QSPI submodule of QSMCM (MPC5xx family)
 - Support for queues in RAM
 - 6 chip selects, expandable to 64 with external demultiplexers
 - Programmable frame size, baud rate, clock delay, and clock phase on a per frame basis
 - Modified SPI mode for interfacing to peripherals with longer setup time requirements
 - Deserial serial interface (DSI)
 - Pin reduction by hardware serialization and deserialization of eTPU and eMIOS channels

Features

- Chaining of DSI submodules
- Triggered transfer control and change in data transfer control (for reduced EMI)
- 2 enhanced serial communication interface (eSCI) modules
 - UART mode provides NRZ format and half or full duplex interface
 - eSCI bit rate up to 1 Mbps
 - Advanced error detection, and optional parity generation and detection
 - Word length programmable as 8 or 9 bits
 - Separately enabled transmitter and receiver
 - LIN Support
 - DMA support
 - Interrupt request support
- 3 FlexCANs
 - 64 message buffers each
 - Full implementation of the CAN protocol specification, Version 2.0B
 - Based on and including all existing features of the Freescale TouCAN module
 - Programmable acceptance filters
 - Short latency time for high priority transmit messages
 - Arbitration scheme according to message ID or message buffer number
 - Listen only mode capabilities
 - Programmable clock source: system clock or oscillator clock
- Nexus development interface (NDI)
 - Per IEEE®-ISTO 5001-2003
 - Real time development support for e200z6 core and eTPU engines through Nexus Class 3 (some Class 4 support)
 - Data trace of eDMA accesses
 - Read and write access
 - Configured via the IEEE® 1149.1 (JTAG) port
 - High bandwidth mode for fast message transmission
 - Reduced bandwidth mode for reduced pin usage
- IEEE® 1149.1 JTAG controller (JTAGC)
 - IEEE® 1149.1-2001 Test Access Port (TAP) interface
 - A JCOMP input that provides the ability to share the TAP. Selectable modes of operation include JTAGC/debug or normal system operation.
 - A 5-bit instruction register that supports IEEE® 1149.1-2001 defined instructions
 - A 5-bit instruction register that supports additional public instructions
 - 3 test data registers: bypass, boundary scan, and device identification

- A TAP controller state machine that controls the operation of the data registers, instruction register and associated circuitry
- Voltage regulator controller
 - Provides a low cost solution to power the core logic. It reduces the number of power supplies required from the customer power supply chip.
- POR block
 - Provides initial reset condition up to the voltage at which pins ($\overline{\text{RESET}}$) can be read safely. It does not guarantee the safe operation of the chip at specified minimum operating voltages.

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